AMENDMENTS TO THE CLAIMS

Listing of Claims

Claim 1 (canceled)

2. (currently amended) An interconnect for testing a semiconductor component having a bumped contact comprising:

a substrate; and

a contact on the substrate configured for electrical engagement with the bumped contact, the contact comprising a recess in the substrate, a plurality of flexible leads cantilevered over the recess configured to support the bumped contact within the recess and to move within the recess, ~~by a distance sufficient to accommodate variations in a size, a shape or a planarity of the bumped contact,~~ each lead comprising ~~a~~ at least one projection and a conductive polymer outer layer on the at least one projection.
~~configured to provide a non-bonding surface for the bumped contact during the electrical engagement.~~

3. (withdrawn) The interconnect of claim 1 wherein the leads comprise a polymer tape attached to the substrate.

4. (withdrawn) The interconnect of claim 1 wherein the leads comprise etched beams on the substrate.

5. (previously presented) The interconnect of claim 2 wherein the bumped contact comprises solder and the conductive polymer outer layer comprises silicone or carbon.

Claims 6-7 (canceled)

8. (previously presented) An interconnect for testing a semiconductor component having a bumped contact comprising:

a substrate having a recess;

a plurality of flexible leads on the substrate cantilevered over the recess configured to electrically engage the bumped contact and to move within the recess by a distance sufficient to accommodate variations in a size, a shape or a planarity of the bumped contact, each lead comprising a projection configured to penetrate the bumped contact, and a conductive polymer outer layer on the projection configured to provide a non-bonding surface for contacting the bumped contact.

9. (previously presented) The interconnect of claim 8 wherein the conductive polymer outer layer comprises a material selected from the group consisting of a carbon film and a metal filled silicone.

10. (previously presented) The interconnect of claim 9 wherein the projection comprises a blade.

11. (previously presented) The interconnect of claim 8 wherein each lead comprises a metal at least partially covered by the conductive polymer outer layer.

12. (currently amended) An interconnect for testing a semiconductor component having a bumped ~~solder~~ contact comprising:

a substrate having a recess;

a plurality of leads on the substrate cantilevered over the recess and configured to move and to electrically

engage the bumped ~~solder~~ contact within the recess, each lead comprising a ~~metal~~ plurality of projections and a conductive polymer outer layer on the projections.
~~metal configured to provide a non-bonding outer surface for contacting the bumped solder contact.~~

13. (withdrawn) The interconnect of claim 12 wherein the leads include a conductive connecting portion proximate to the recess for electrically connecting the leads to one another.

Claim 14-15 (canceled)

16. (withdrawn) The interconnect of claim 12 wherein the bumped contact comprises solder and the leads comprise a non-solder wettable metal.

17. (currently amended) The interconnect of claim 12 wherein the conductive polymer outer layer comprises a material selected from the group consisting of carbon and silicone.

18. (currently amended) The interconnect of claim 12 wherein the leads and the projections comprise a metal.
~~further comprising at least one projection on each lead.~~

Claims 19-30 (canceled)

31. (currently amended) A system for testing a semiconductor component having a bumped contact comprising:

a testing apparatus;

an interconnect on the testing apparatus comprising:

a substrate having a recess;

a plurality of leads on the substrate configured for electrical engagement with the bumped contact, each

lead cantilevered over the recess and configured to move within the recess during the electrical engagement, each lead comprising a projection and a conductive polymer outer layer on the projection.
~~configured to provide a non-bonding outer surface for the bumped contact during the electrical engagement.~~

32. (previously presented) The system of claim 31 wherein the conductive polymer outer layer comprises a material selected from the group consisting of carbon and silicone.

33. (withdrawn) The system of claim 31 wherein the leads comprise a polymer tape attached to the substrate and comprising an electrical connector configured in electrical communication with the connecting segment and the test circuitry.

Claims 34-48 (canceled)